

# Chapter 5:

## Introduction of Cryomodule

Typical operating temperature of SRF cavities is 1.8 K~4.5 K

Helium circuit:

SRF cavities are immersed in liquid helium (helium vessel)

Helium supply and return lines are connected to helium vessel

Helium vessel can be pumped down to get lower temperature

Thermal design:

Minimize thermal loss

Typically uses multi-layer insulation and intermediate temperature boundary in a vacuum chamber

Power coupler: Couples RF power to a cavity

Mechanical tuner

Keeps a cavity on resonance or within a certain range of detuning

HOM coupler: Couples HOMs → damp and extract HOM

Magnetic shielding: Reduces ambient magnetic field

# Keep cold efficiently

One of the major concerns in cryomodules.

Large scale refrigeration plant is also one of major challenges for large scale machines

Need a very careful consideration in thermal and safety points of view.

thermal: minimize thermal loss or optimize operating condition

safety: cryogenic incident (machine protection, personnel protection)

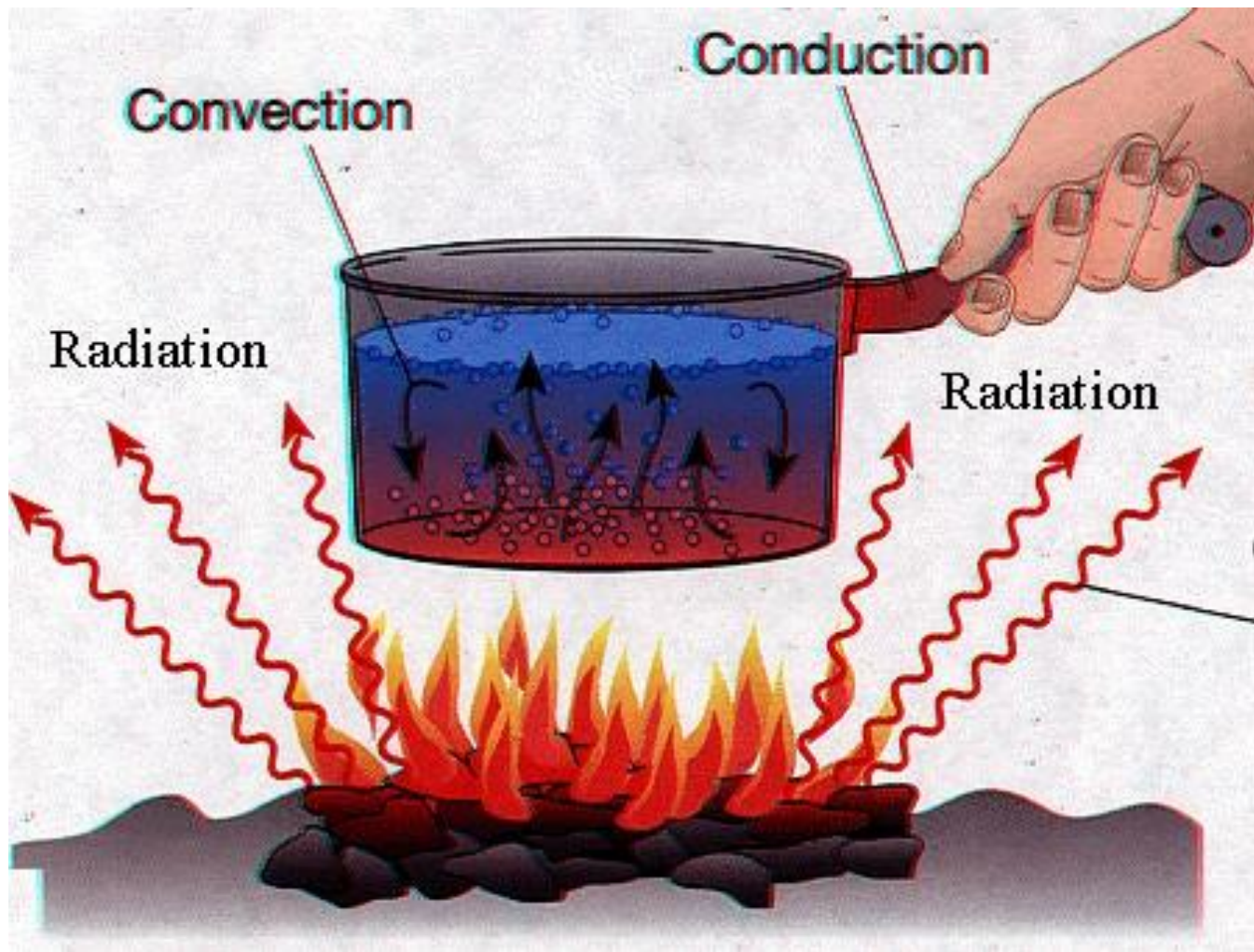
Insulation: reduce thermal heat transfer

convection: vacuum chamber

conduction: penetrations, supporting structures

thermal radiation: Multilayer insulation (MLI), thermal shield

# Heat Transfer



# Conduction heat transfer

When a temperature gradient exists in a body or between objects that are in physical contact, there's an energy transfer from the high temperature region to the low temperature region.

The heat transfer rate is proportional to area, temperature gradient

$$q = -kA \frac{\partial T}{\partial x} [W]$$

where  $A$  : area for conduction

$k$  : proportional constant called thermal conductivity (material property)  
function of a temperature

$\frac{\partial T}{\partial x}$  : temperature gradient

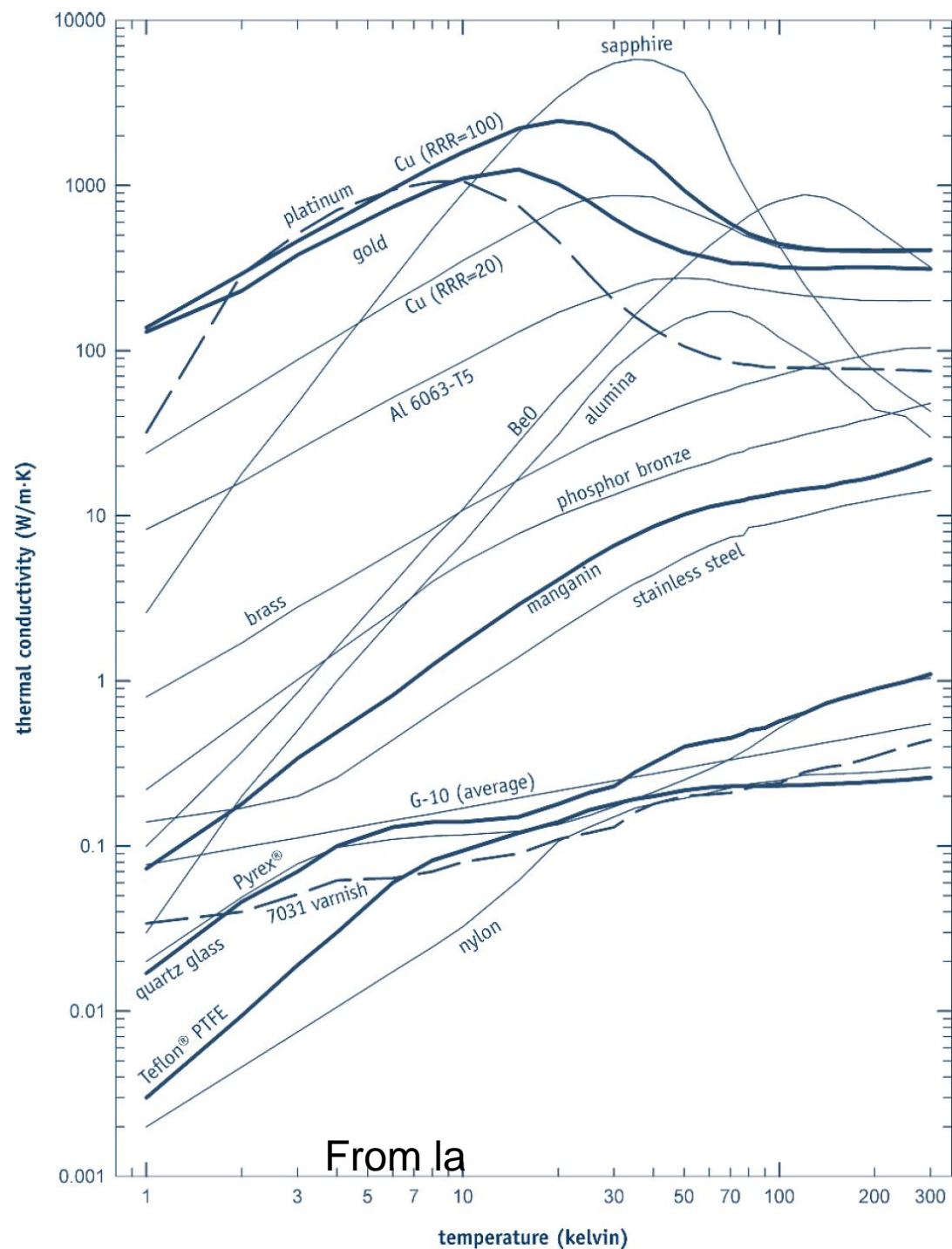
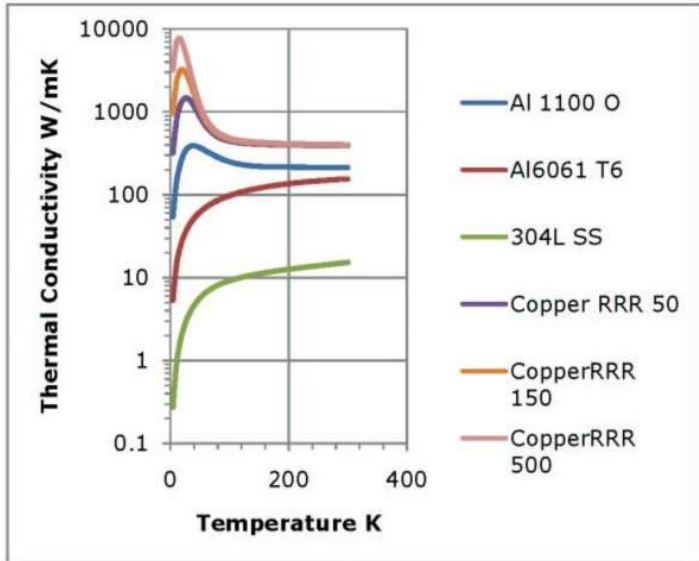
Ex. Each end of rod (2cm dia. And 0.5m long) is connected to thermal boundaries at 4K and 300 K.

Stainless steel: assume constant  $k=3$  W/mK  $\rightarrow q=1*\pi*1e-4*296/0.5=0.568$  W

Copper: assume constant  $k=300$  W/mK  $\rightarrow q=1*\pi*1e-4*296/0.5=56.8$  W

Thermal conductivity is a function of material

When one performs a thermal analysis in large temperature range, non-linear analysis is essential using a FEM code.



# Convection heat transfer

Heat transfer occurring due to the bulk motion of fluid (gas, liquid).

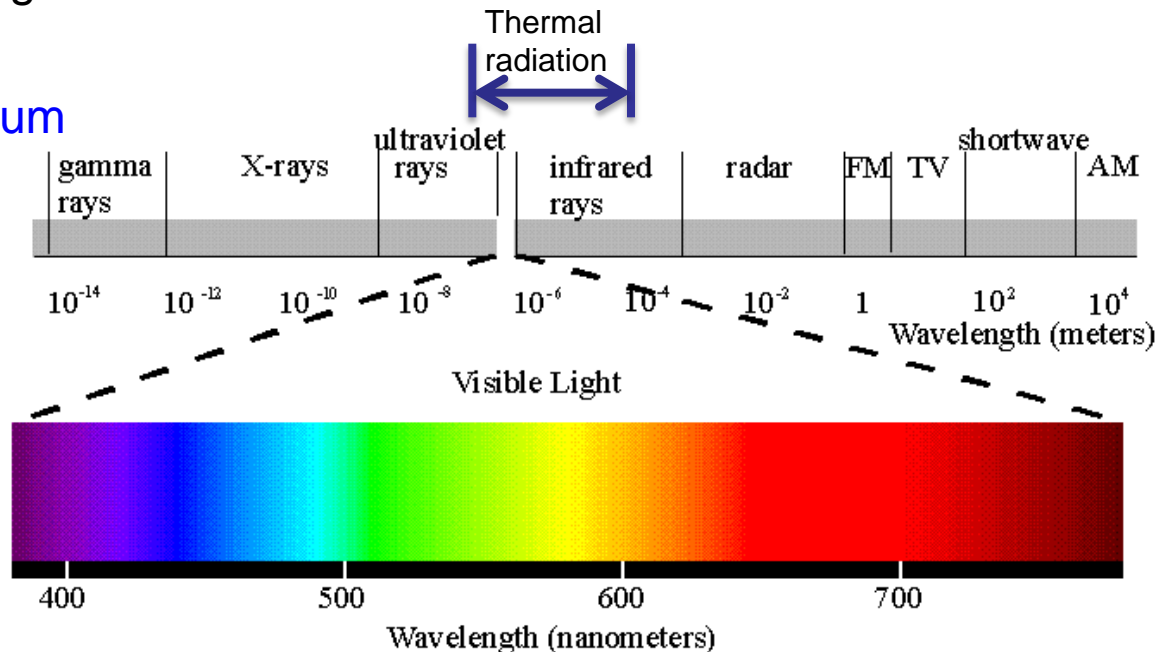
The transfer of energy between an object and its environment, due to fluid motion.

Pressure  $< 10^{-4}$  torr: negligible effect

# Radiation heat transfer

The transfer of energy to or from a body by means of the emission or absorption of electromagnetic radiation

## Electromagnetic Spectrum



Energy radiated per unit time and per unit area by the ideal radiator is given by the Stefan-Boltzmann law:

$$E_b = \sigma T^4 \quad \text{where } \sigma \text{ is the Stefan - Boltzmann constant, } 5.669 \times 10^{-8} \text{ W}/(\text{m}^2 \cdot \text{K}^4)$$

Ex.) Heat exchange between non-blackbodies

1) Two infinitely parallel plates  $\rightarrow q/A = \frac{\sigma(T_1^4 - T_2^4)}{1/\epsilon_1 + 1/\epsilon_2 - 1}$

2) Two long concentric cylinders  $\rightarrow q = \frac{\sigma A_1(T_1^4 - T_2^4)}{1/\epsilon_1 + (A_1/A_2)(1/\epsilon_2 - 1)}$

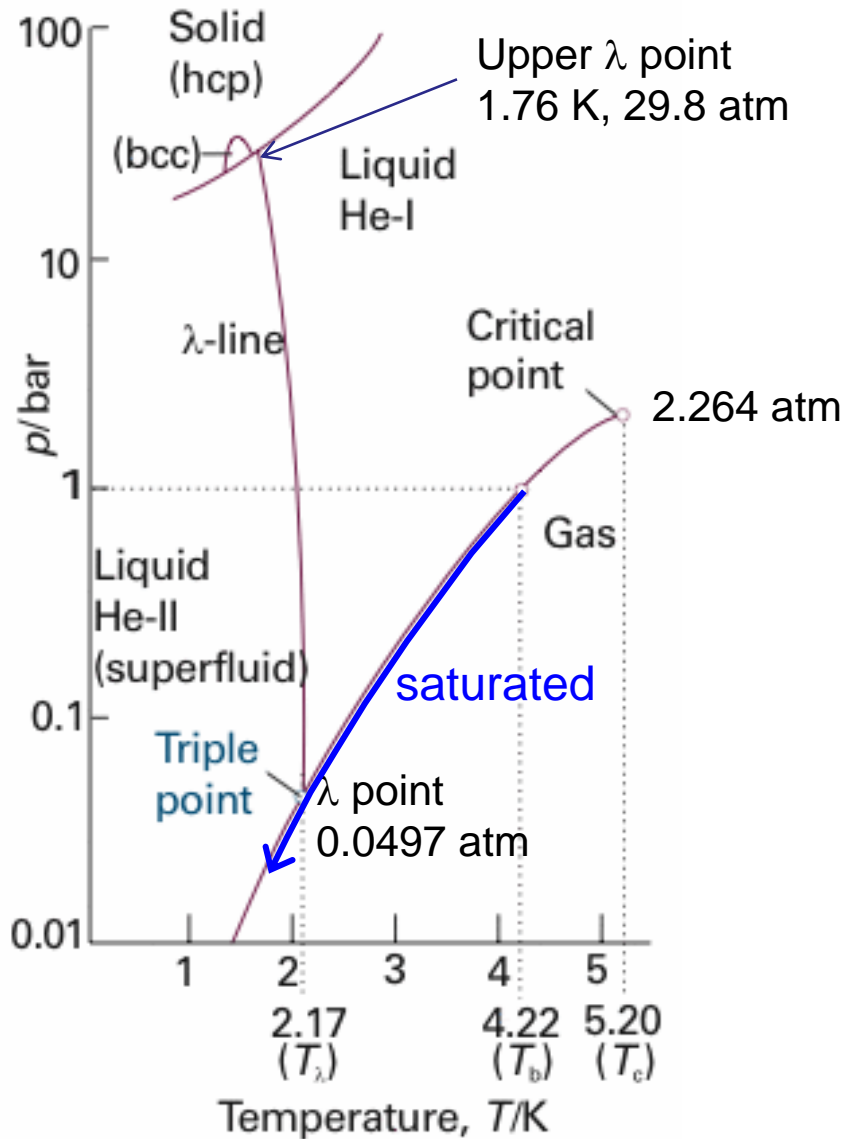
Inner cylinder:  $T_1, A_1, \epsilon_1$   
 Outer cylinder:  $T_2, A_2, \epsilon_2$



3) layers of low emissivity material and insulators.

$$\text{Ideally } (q/A)_{\text{with shields}} = (q/A)_{\text{without shield}} / (1+n), \quad n = \text{number of layers}$$

# Phase diagram of $^4\text{He}$

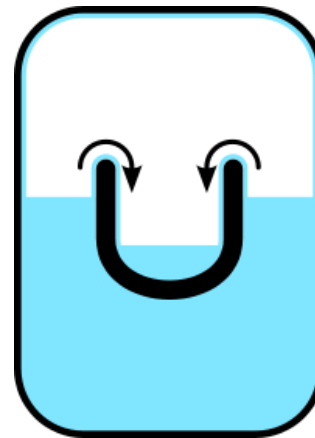


Superfluid:

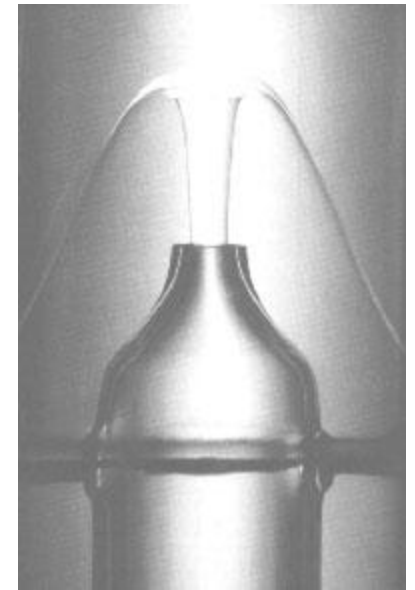
A phase of matter in which viscosity of a fluid vanishes.

Discovered in 1937 by Kapitza, Allen, and Misener.

L. Landau won the Nobel Prize in Physics 'phenomenological and semi-microscopic theory of superfluidity of  $^4\text{He}$ '.



Film creeping



Thermo-caloric effect



# Cryogenic efficiency

Ideal Carnot efficiency

$$\eta_{\text{ideal}} = \frac{T_{\text{op}}}{T_{\text{ambient}} - T_{\text{op}}}$$

Ex. Ideal case:  $\eta_{\text{ideal}}=0.345$  for 300K $\rightarrow$ 77K,

$\eta_{\text{ideal}}=0.014$  for 300K $\rightarrow$ 4.2K

In practice, actual efficiency is much lower than this ideal case.

$\eta/\eta_{\text{ideal}} = \eta_{\text{ratio}}$  typically ranges 0.1~0.35 (<0.1 in small systems)

Smaller machine has lower efficiency.

As technologies improve, efficiencies are getting higher.

Some reference numbers for scaling

Room temperature power/power at 4.5 K: 250~350

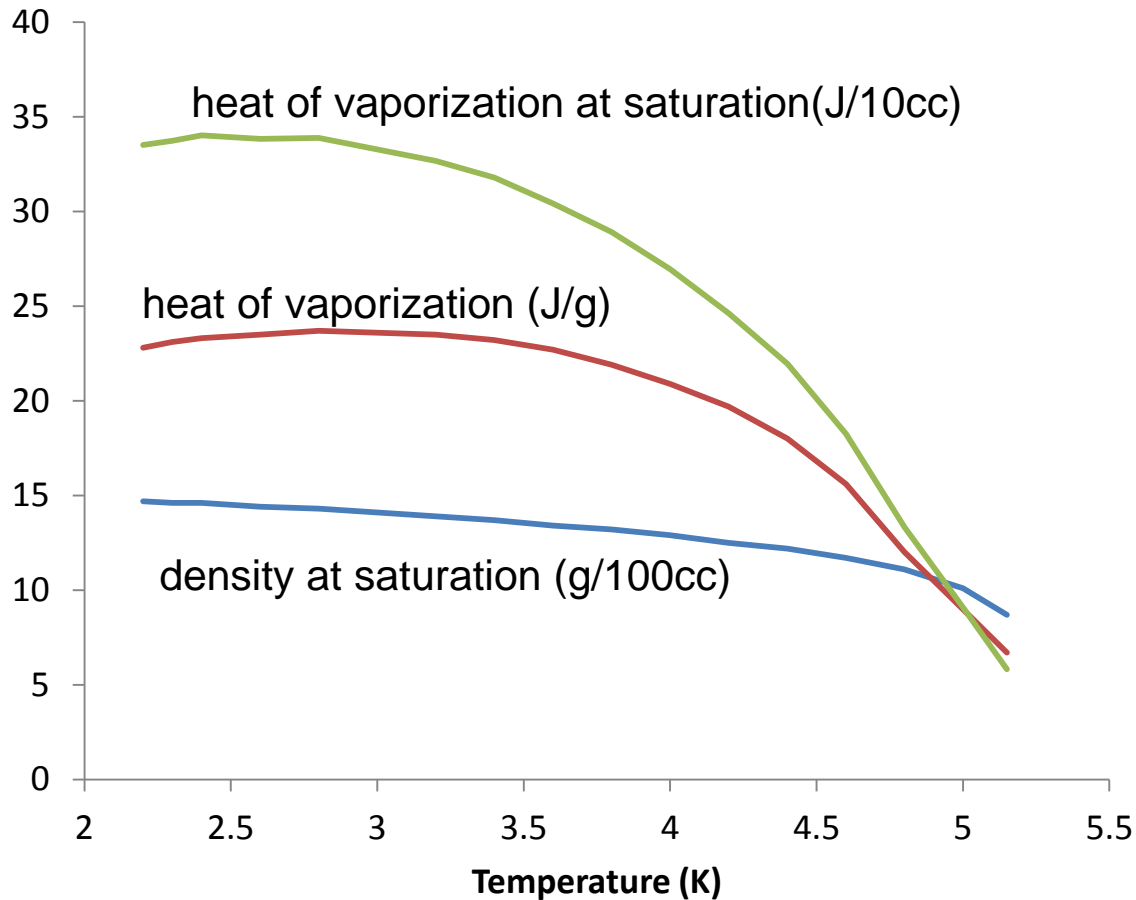
Room temperature power/power at 2 K: 1100~1300

Rough scaling:

If we have 100 W load at 2 K  $\rightarrow$  we need ~120 kW cryogenic system at least.

(we will re-visit this concern for machine efficiency estimation in Chapter 7)

# Helium properties at saturation



Low efficiency + small heat capacity + expensive: need very careful design

# Ex. SNS Refrigerator System

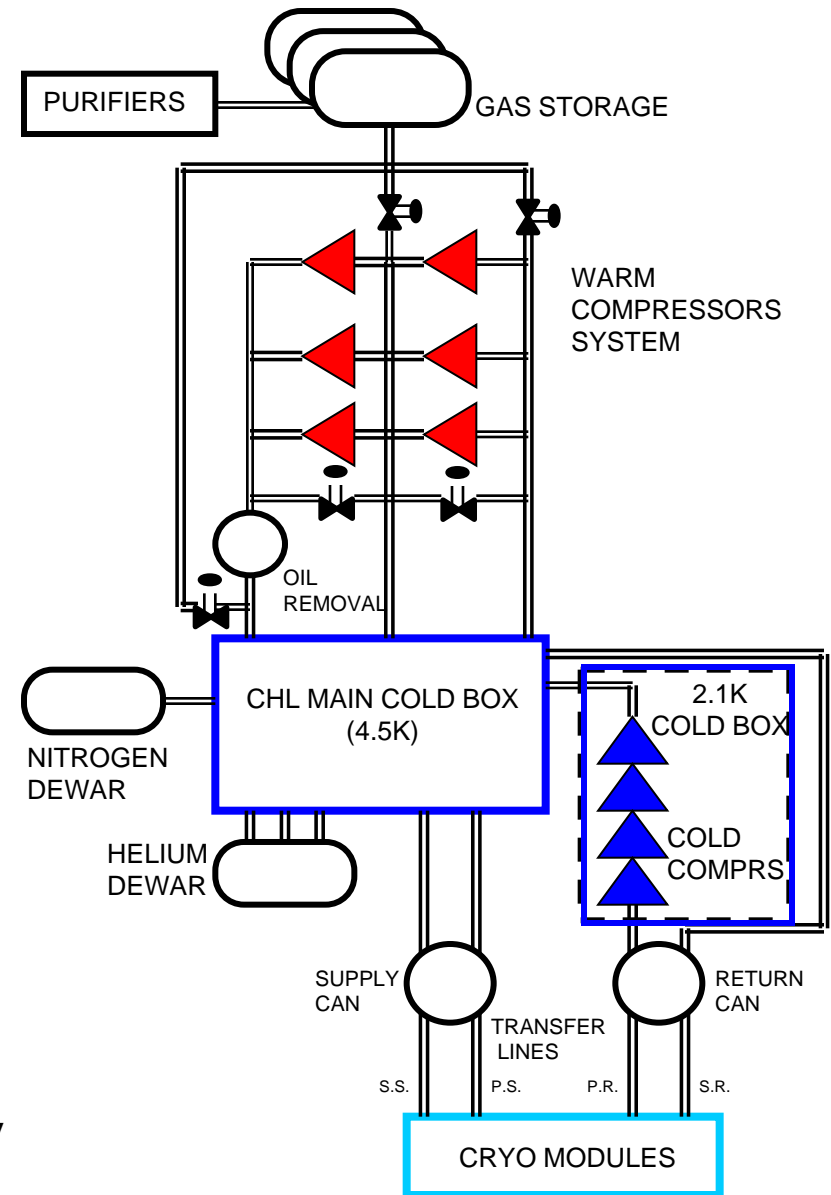
## Helium Refrigerator System

2400 Watt Capacity @ 2.1 Kelvin and  
8300 Watt Shield Load @ 38/50 Kelvin  
15g/s Liquefaction at 4.5 Kelvin  
80g/s Liquefaction Mode

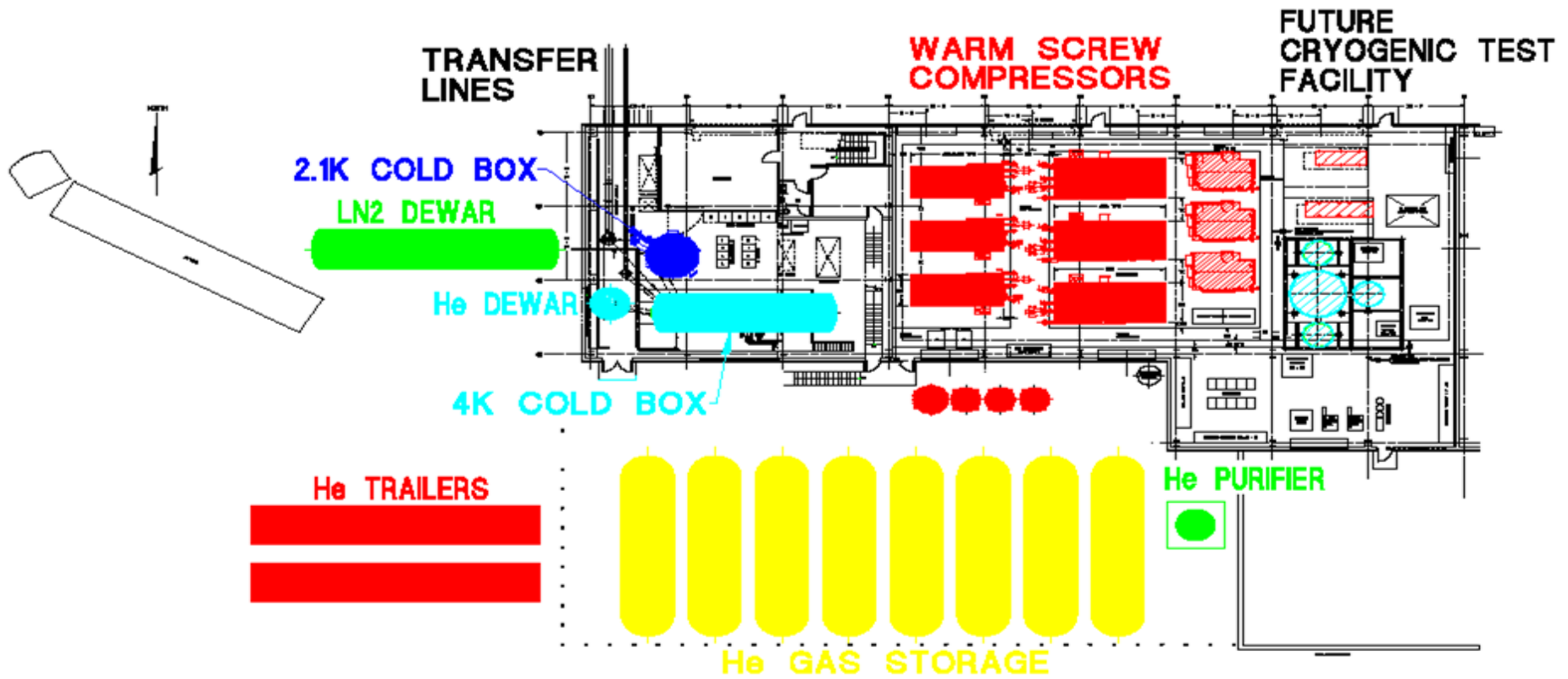
## Cryogenic Transfer Line System

4.5K & 38K Helium Supply and  
4.0K & 50K Helium Return

Whole system consumes >3 MW electricity



# SNS CHL layout



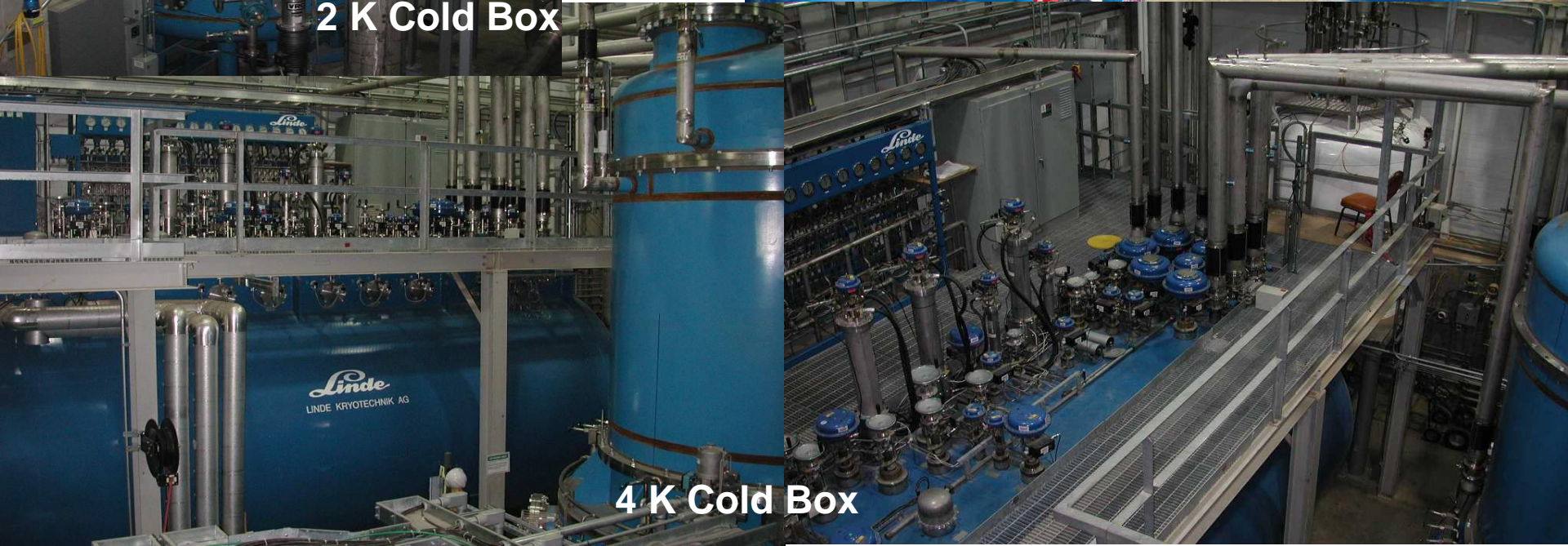




2 K Cold Box

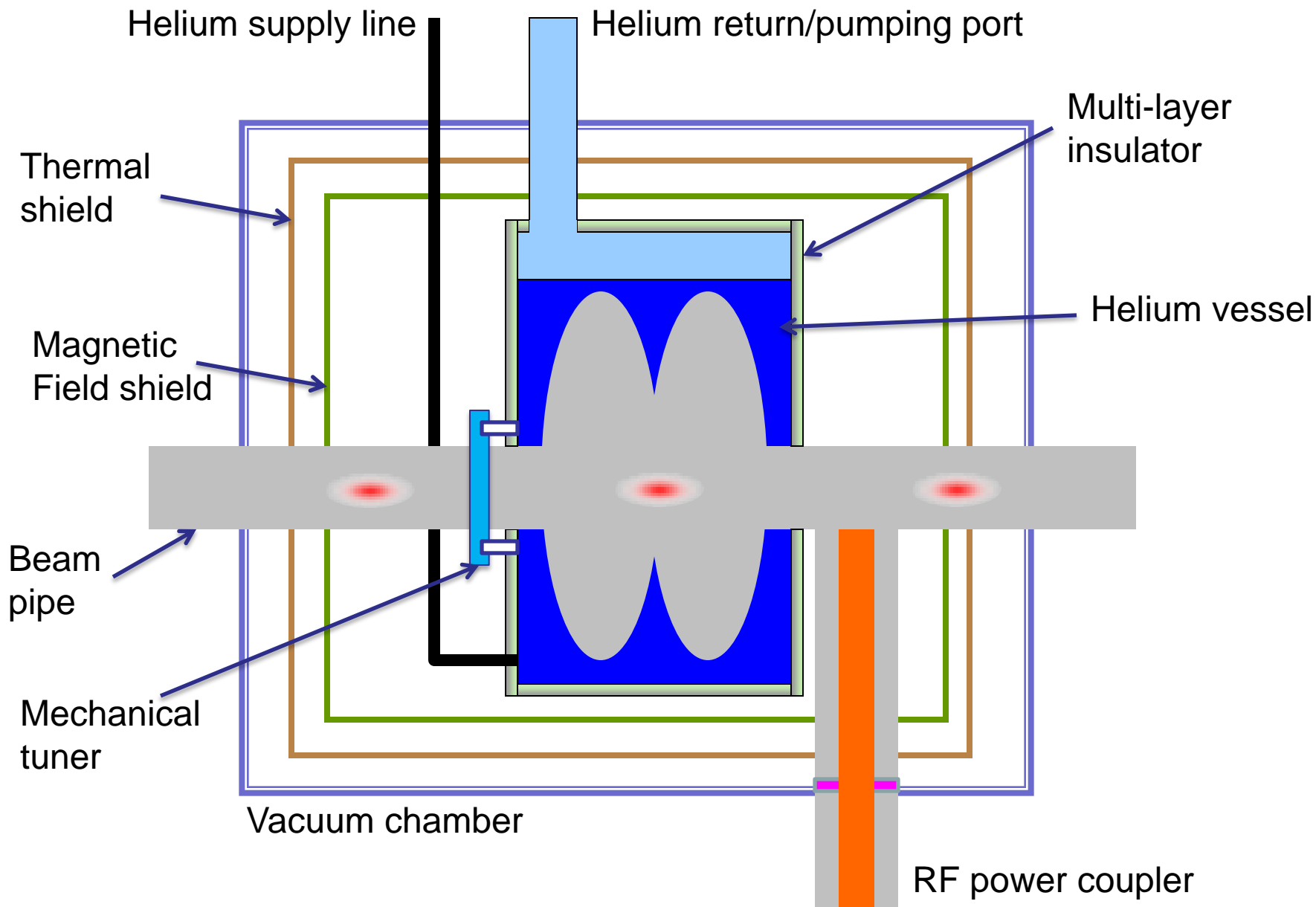


Warm Compressor



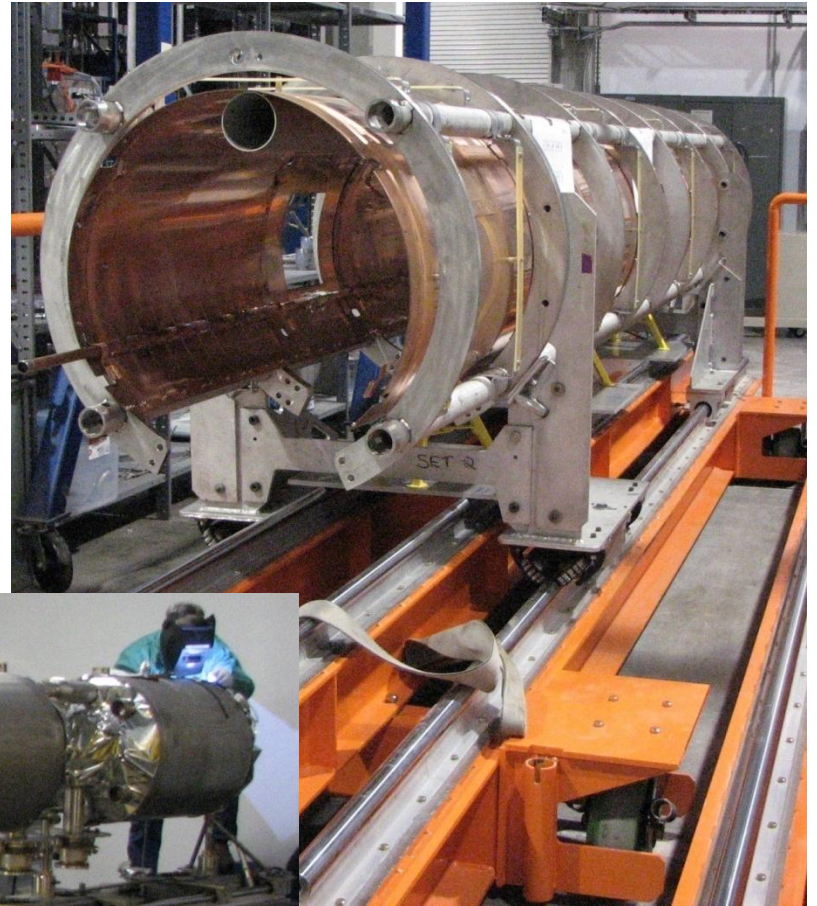
4 K Cold Box

# Schematics of cryomodule





Space frame and thermal shield



Cavity string



Cavity with Helium vessel

# Ex: SNS Cryomodule

End can for Helium supply

End can for Helium return

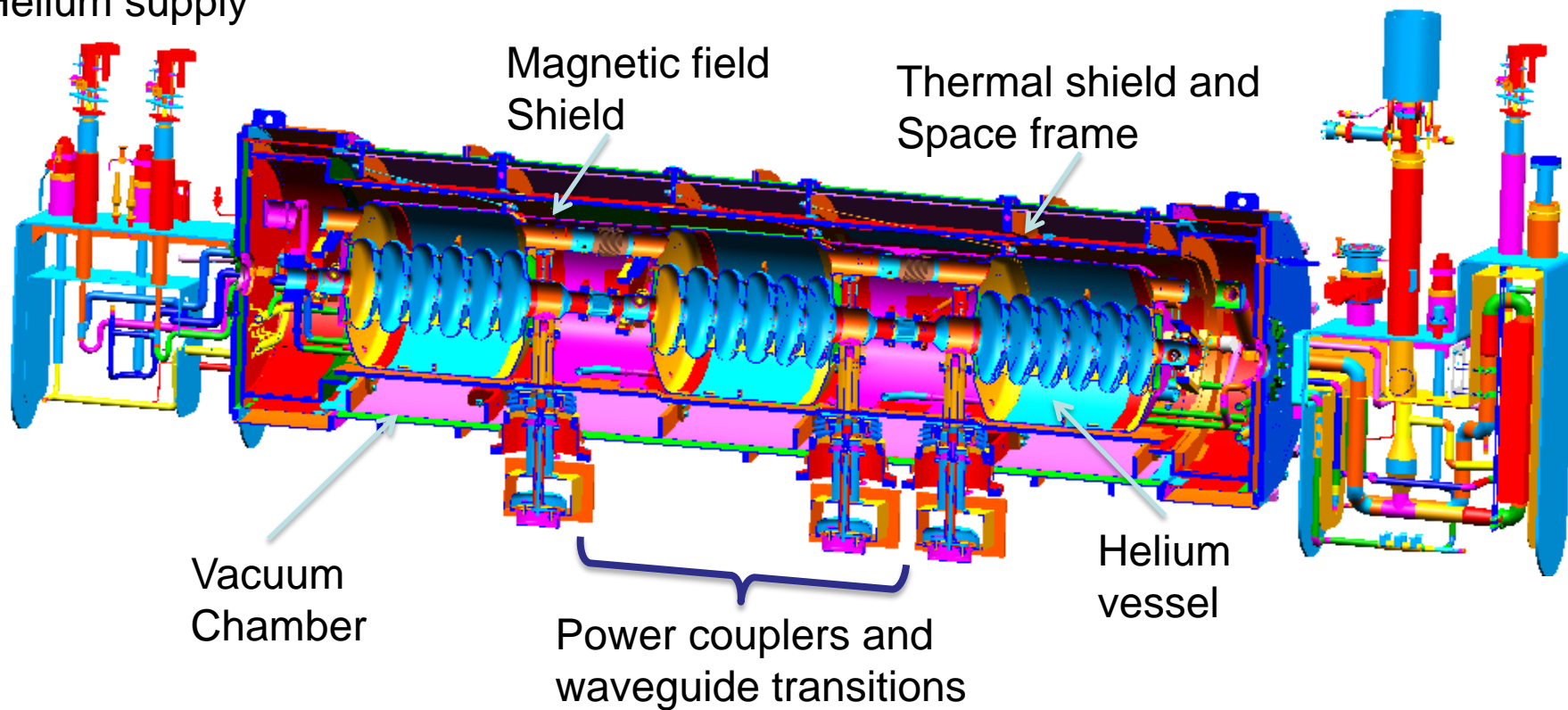
Magnetic field Shield

Thermal shield and Space frame

Vacuum Chamber

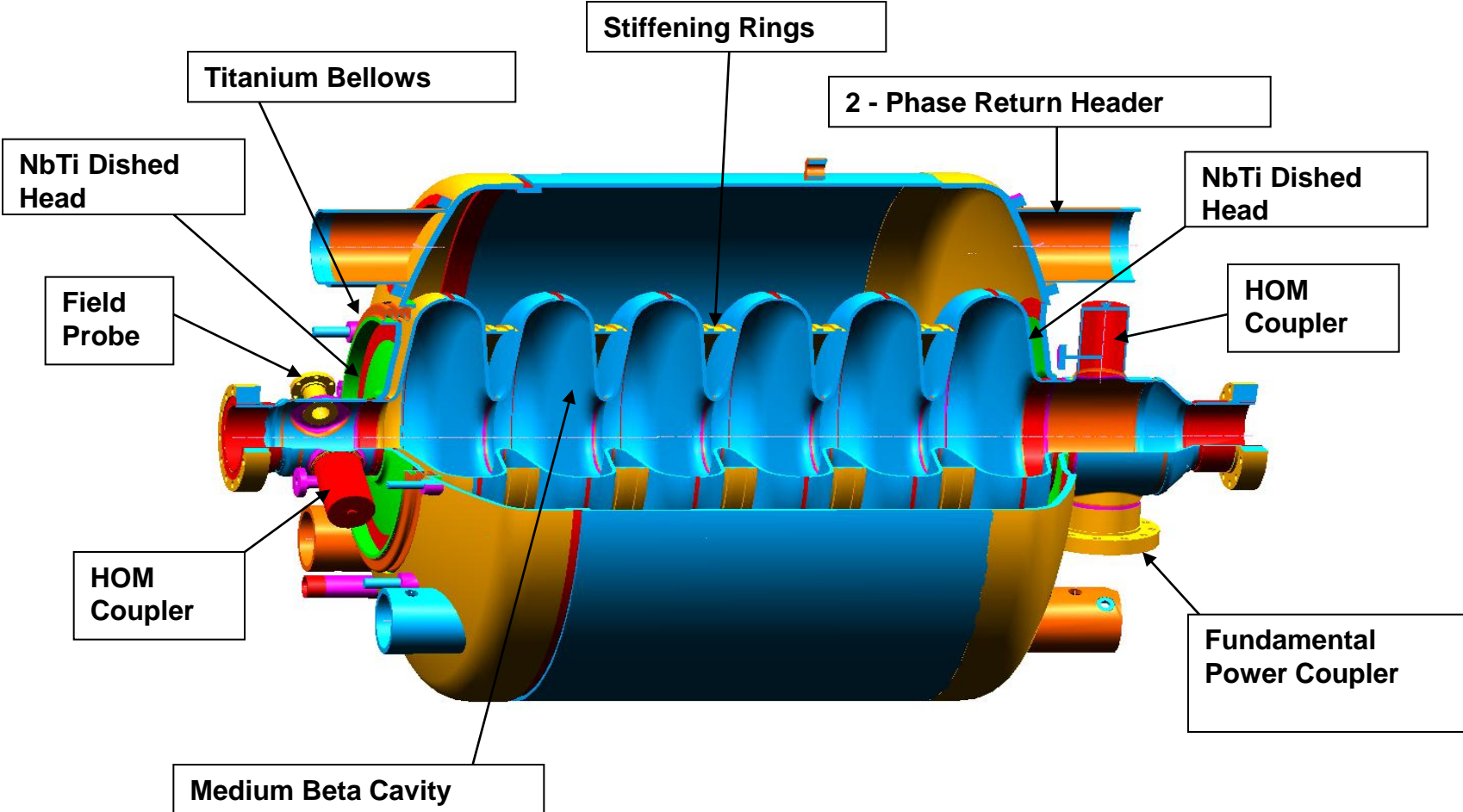
Power couplers and waveguide transitions

Helium vessel

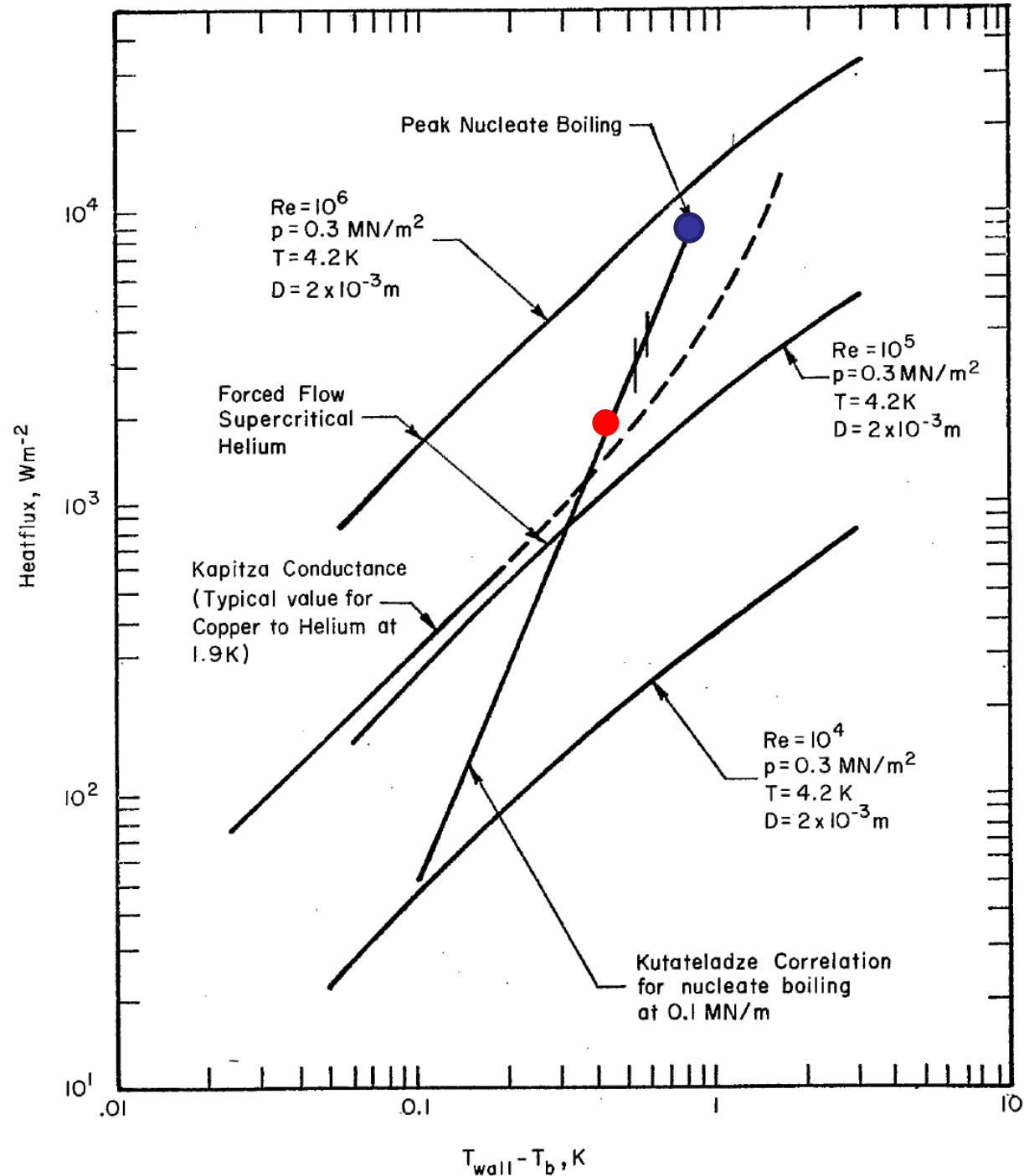
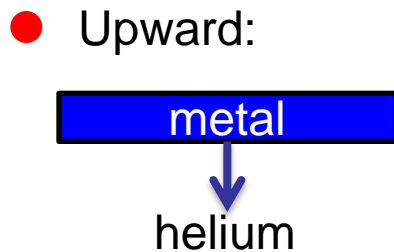
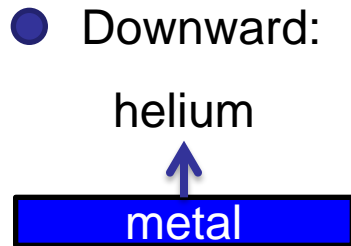




# Ex. SNS Cavity Assembly



# Comparisons of various modes of helium heat transfer



# Resonance frequency control

## Slow tuner (mechanical tuner):

Compensate static or quasi-static detuning  
(initial offset or slow drift of resonance frequency)

Compress/expand cavity length typically using stepper motor

Coarse tuning: usually put the resonance frequency in the allowable band

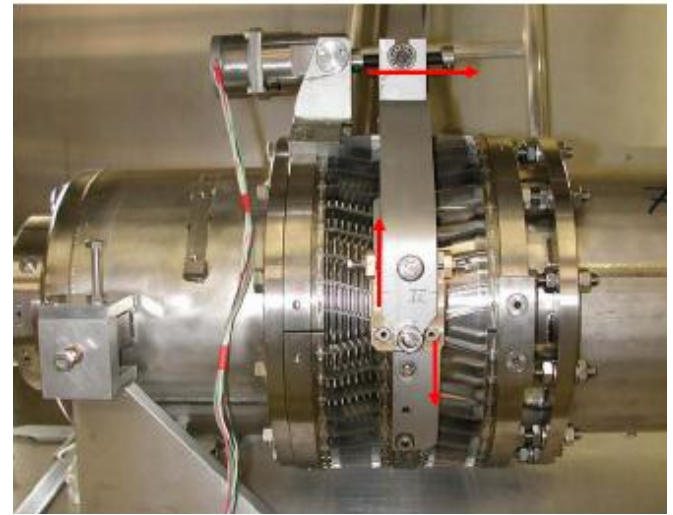
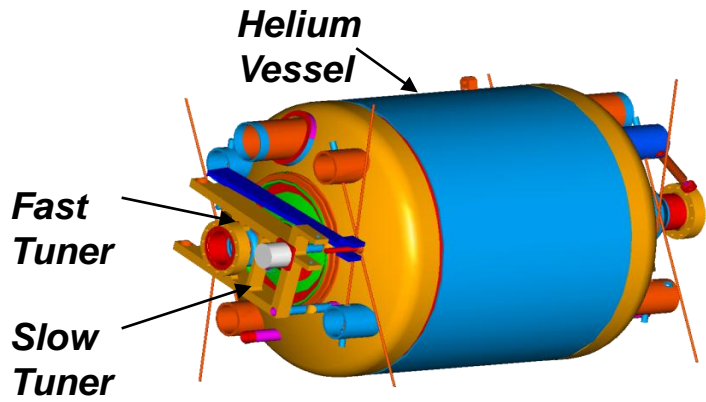
Typical tuning range: about +/- few mm

Types:

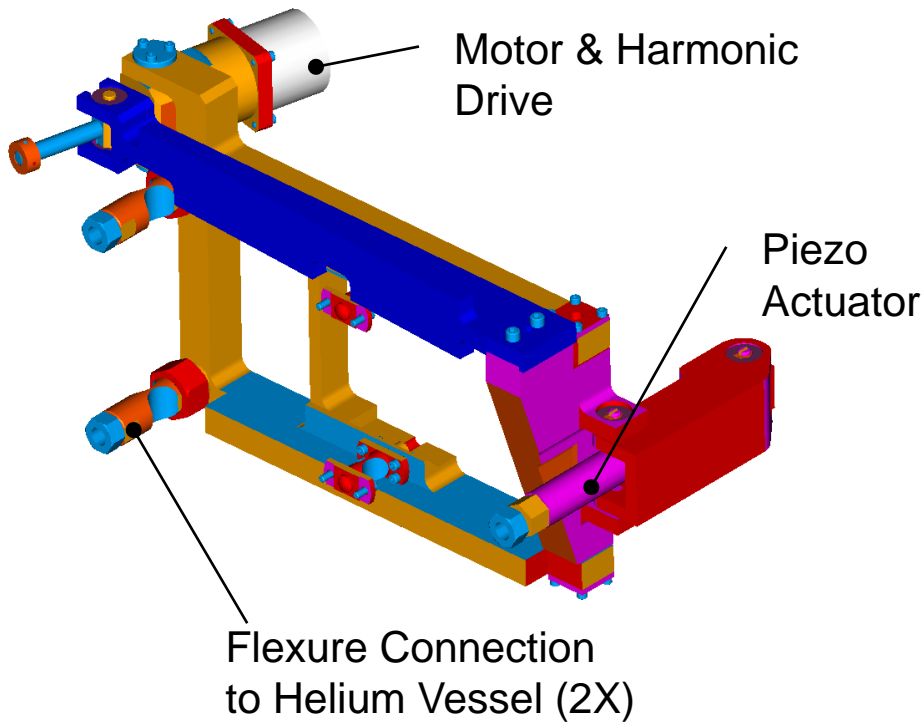
CEA/Scalay tuners

blade tuner (DESY, INFN)

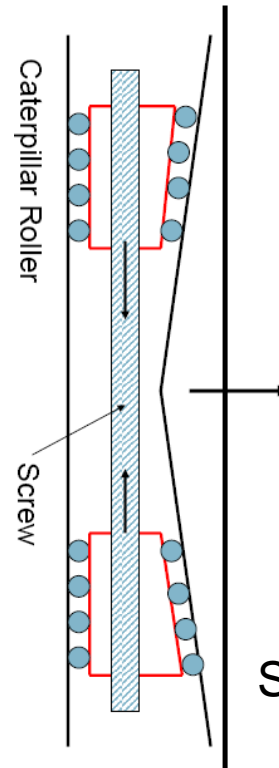
side jack tuner (KEK)



INFN, Blade tuner for ILC



SNS tuner (saclay-TTF generation I type)



Side Jack tuner (KEK)

## Fast tuner:

Fine & fast tuning

Pulsed operation: Compensate Lorentz force detuning within RF pulses

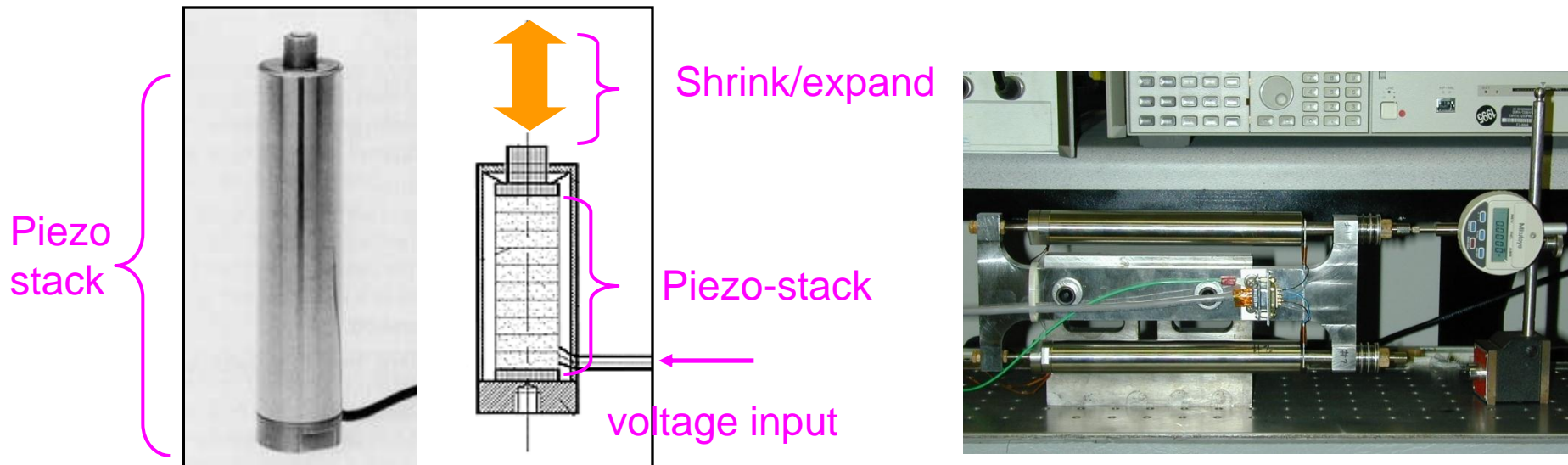
High  $Q_{\text{ext}}$ : Compensate microphonics

Piezoelectric actuators: electromechanical actuator. Linear electromechanical interaction between the mechanical and the electrical state in piezoelectric materials.  
typical tuning range: few to several  $\mu\text{m}$

magnetostrictive actuator: solid state magnetic actuator. A current driven coil surrounding the magnetostrictive rod generates the expansion of the rod.

# Piezoelectric actuator

Voltage is applied to the piezoelectric actuator device which make the piezo stack shrink/expand



Typically

Stroke: 70~80 mm for 100 mm stack at room temperature

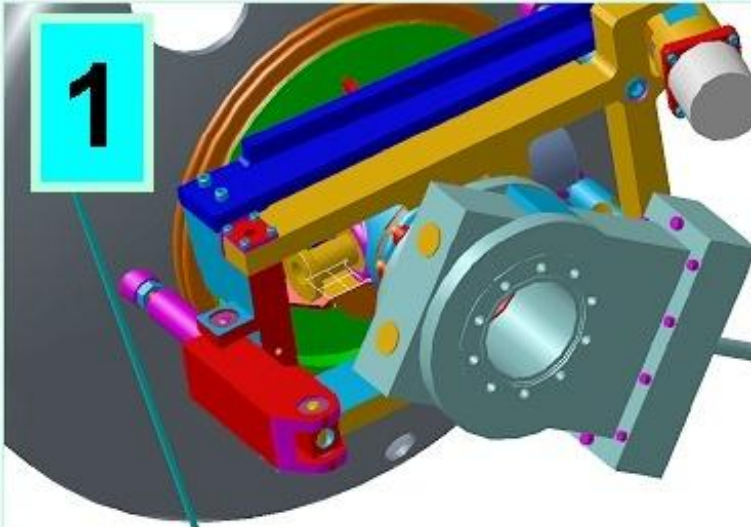
stroke at cryogenic temperature  $\rightarrow$  5~10 % of that at room temperature

Resolution: ~Hz



# Model vs. Reality

1



1. On the CAD Model

2



3. Reality – Pretty Complicated

3

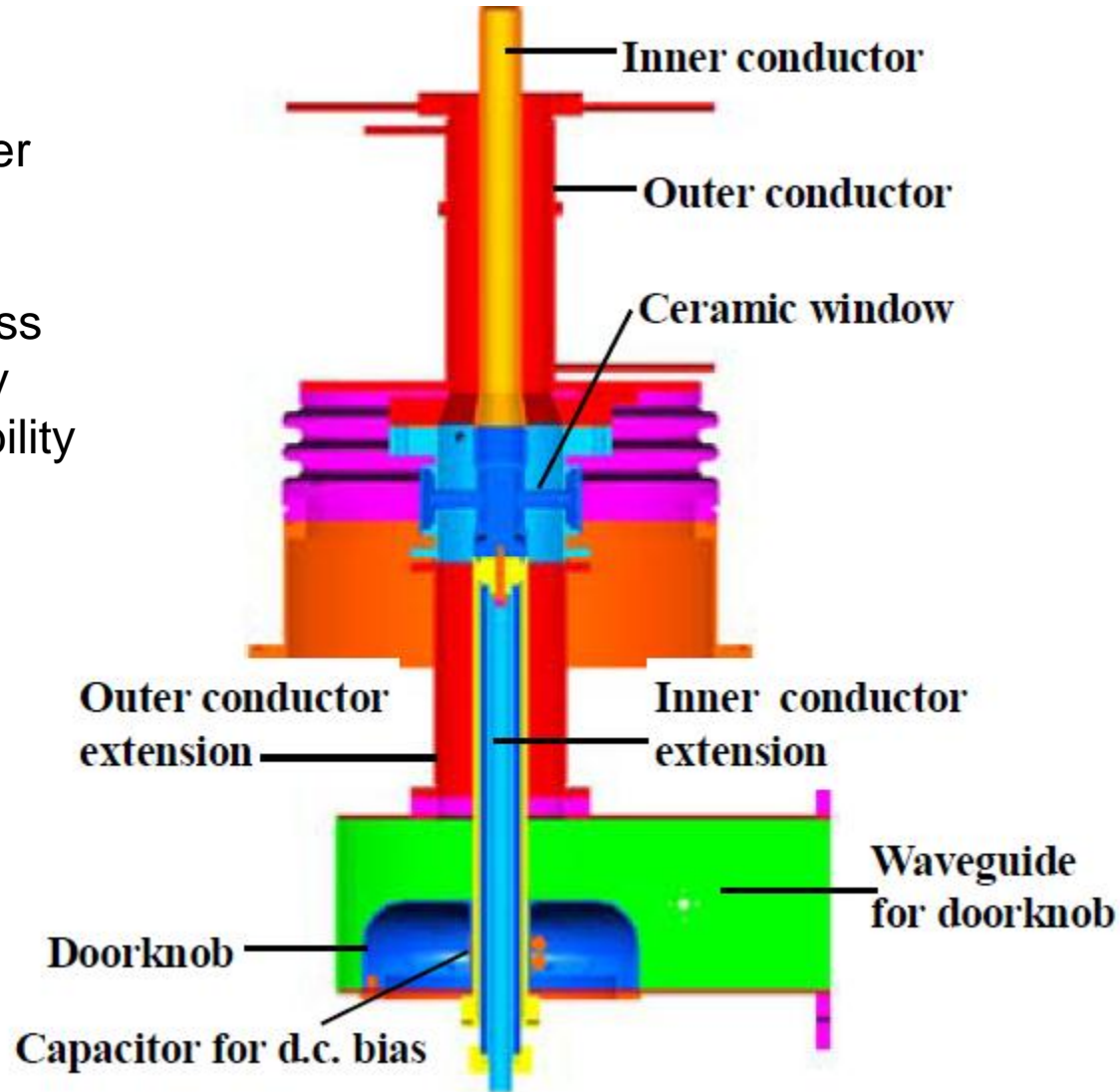


# Power Coupler

Function: Deliver RF power  
Coupling  $\rightarrow Q_{ex}$

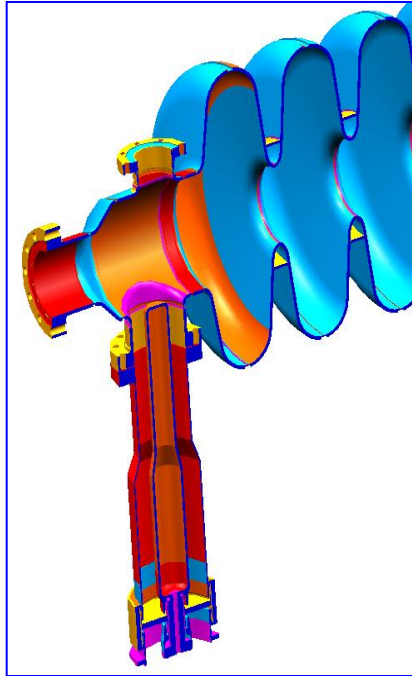
Concerns: Transmission loss  
Thermal stability  
Mechanical stability  
Simplicity  
Reliability  
Cost  
Multipacting

Frequency  
Power needed  
Coupling  
Types  
Cooling  
Window

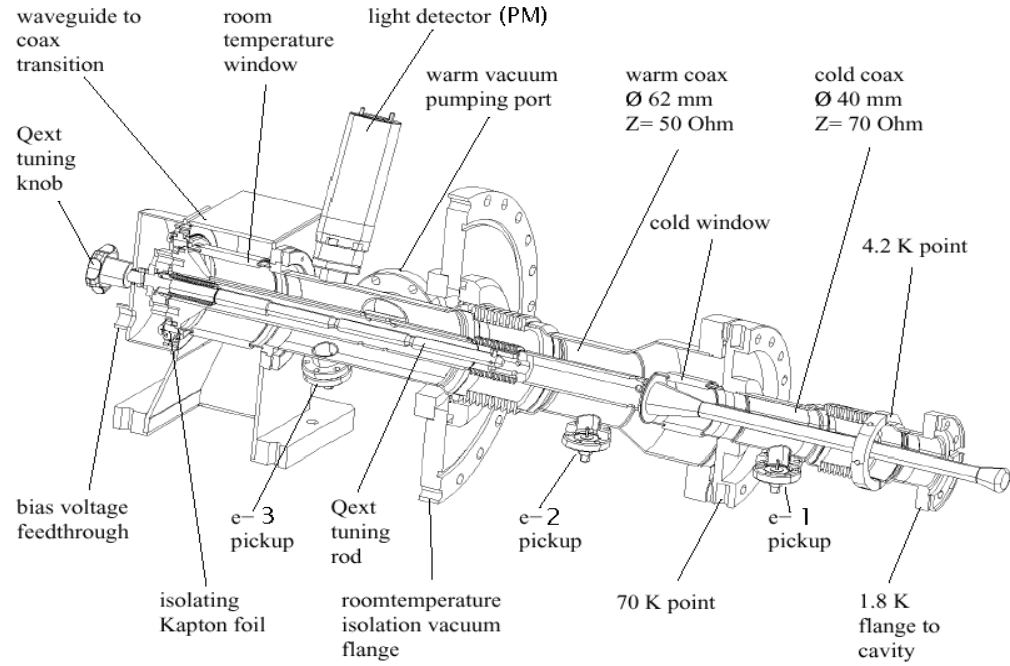




# Coaxial

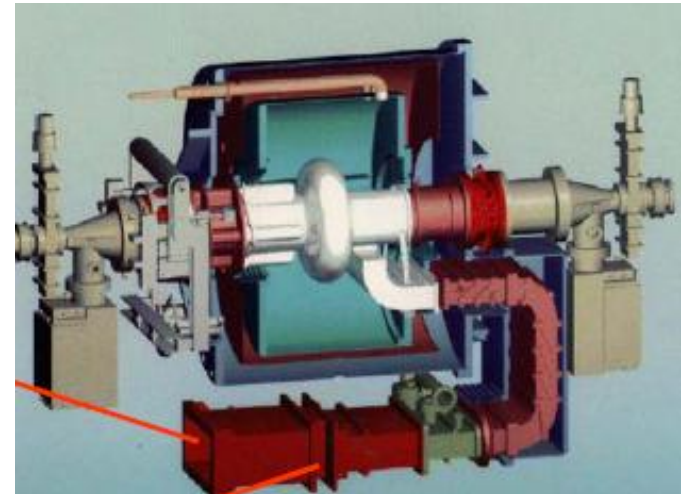


SNS power coupler

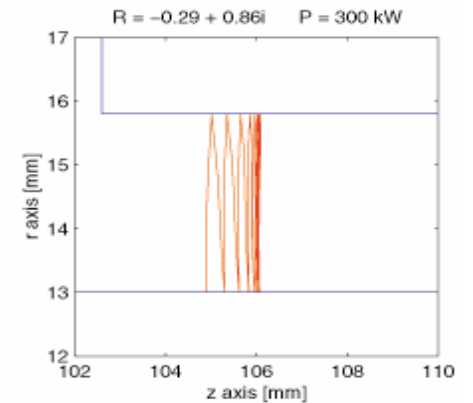
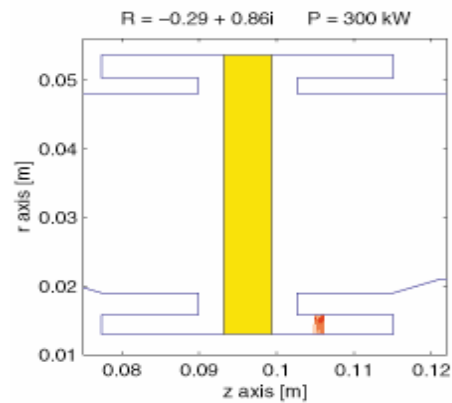
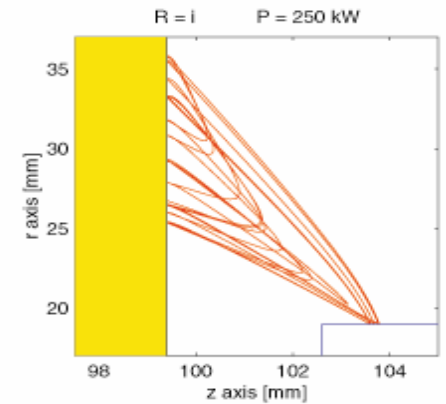
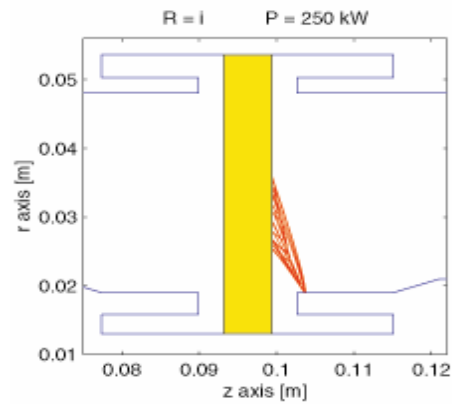
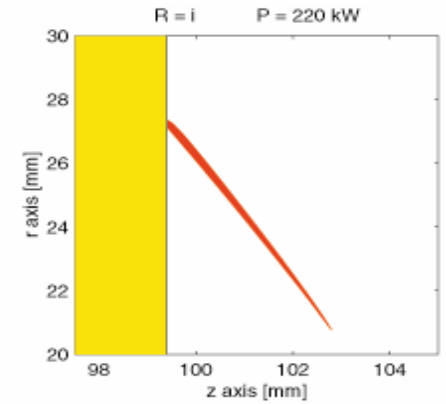
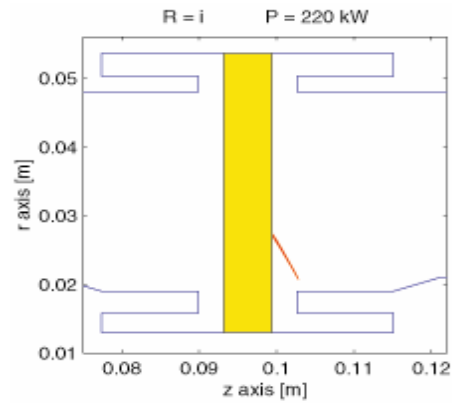
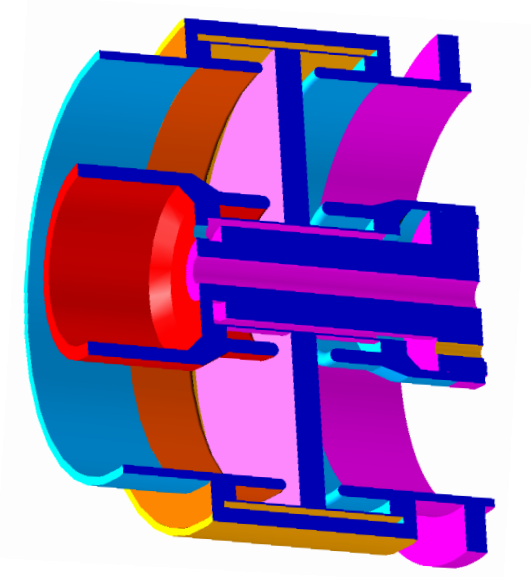


TTF3 coupler (ILC)

# Waveguide



# Multipacting simulations around ceramic window



# Coupler conditioning

